



### General Description

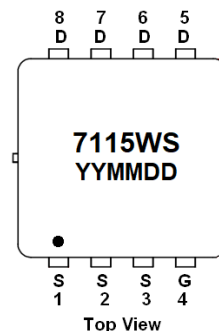
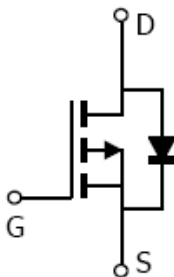
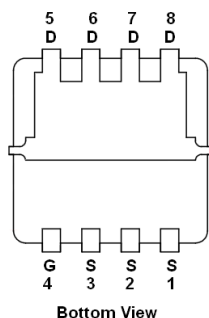
AFP7115WS, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

### Features

- -100/-4.0A,  $R_{DS(ON)} = 190m\Omega @ V_{GS} = -10V$
- -100/-3.2A,  $R_{DS(ON)} = 210m\Omega @ V_{GS} = -4.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- DFN3.3X3.3-8L package design

### Pin Description ( DFN3.3X3.3-8L )



### Application

- DC-DC Converter
- POL

### Pin Define

Pin	Symbol	Description
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5	D	Drain
6	D	Drain
7	D	Drain
8	D	Drain

### Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFP7115WSFN308RG	7115WS	DFN3.3X3.3-8L	Tape & Reel	5000 EA

※ YY year code

※ MM month code

※ DD date code

※ AFP7115WSFN308RG : 13" Tape & Reel ; Pb- Free ; Halogen -Free



### Absolute Maximum Ratings

( $T_A=25^\circ\text{C}$  Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	$V_{DSS}$	-100	V
Gate –Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current( $T_J=150^\circ\text{C}$ )	$I_D$	$T_C=25^\circ\text{C}$	-4.0
		$T_C=70^\circ\text{C}$	-3.2
Pulsed Drain Current	$I_{DM}$	-6.0	A
Continuous Source Current(Diode Conduction)	$I_S$	-3.0	A
Power Dissipation	$P_D$	$T_A=25^\circ\text{C}$	28
		$T_A=70^\circ\text{C}$	18
Operating Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55/150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	120	$^\circ\text{C/W}$

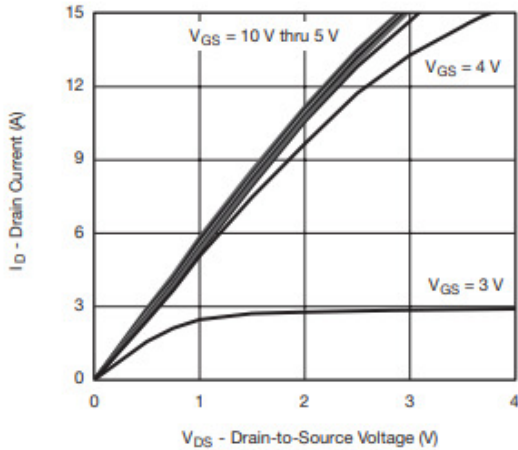
### Electrical Characteristics

( $T_A=25^\circ\text{C}$  Unless otherwise noted)

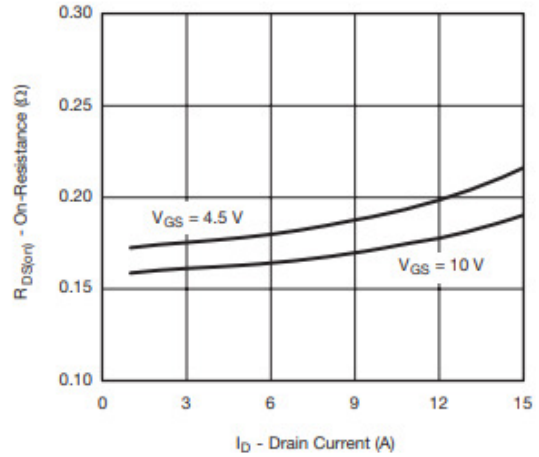
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D = -250\mu A$	-100			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D = -250\mu A$	-1.0		-2.5	
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS} = \pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -80V, V_{GS}=0V$			-1	
		$V_{DS} = -80V, V_{GS}=0V$ $T_J=85^\circ\text{C}$			-30	$\mu A$
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq -10V, V_{GS} = -10V$	-18			A
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -4.0A$		165	190	m $\Omega$
		$V_{GS} = -4.5V, I_D = -3.2A$		185	210	
Forward Transconductance	$g_{FS}$	$V_{DS} = -15V, I_D = -3.2A$		12		S
Diode Forward Voltage	$V_{SD}$	$I_S = -2A, V_{GS}=0V$		-0.8	-1.3	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS} = -50V, V_{GS} = -4.5V$ $I_D = -3.6A$		12	20	nC
Gate-Source Charge	$Q_{gs}$			3.5		
Gate-Drain Charge	$Q_{gd}$			5.0		
Input Capacitance	$C_{iss}$	$V_{DS} = -50V, V_{GS} = 0V$ $f = 1\text{MHz}$		1100		pF
Output Capacitance	$C_{oss}$			70		
Reverse Transfer Capacitance	$C_{rss}$			45		
Turn-On Time	$t_{d(on)}$	$V_{DD} = -50V, R_L = 17\Omega$ $I_D = -2.8A, V_{GEN} = -10V$ $R_G = 1\Omega$		8	15	ns
	$t_r$			15	20	
Turn-Off Time	$t_{d(off)}$			35	50	
	$t_f$			10	20	



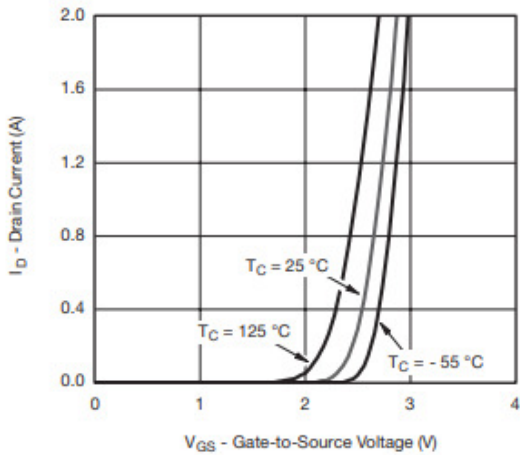
## Typical Characteristics



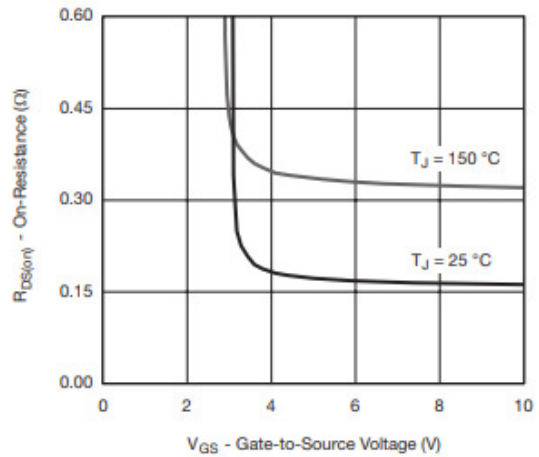
Output Characteristics



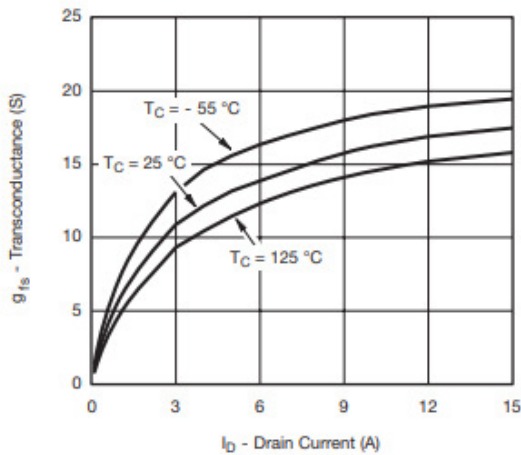
On-Resistance vs. Drain Current



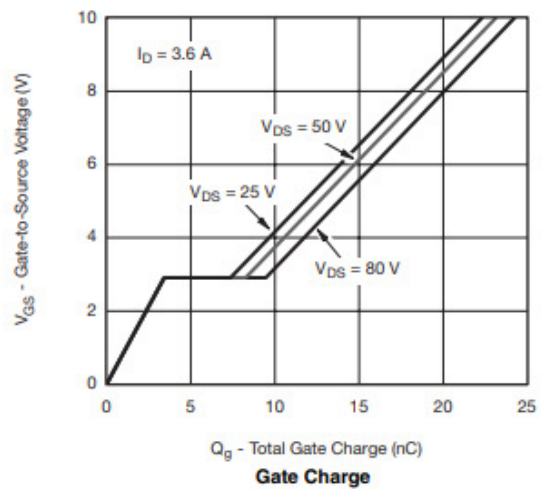
Transfer Characteristics



On-Resistance vs. Gate-to-Source Voltage



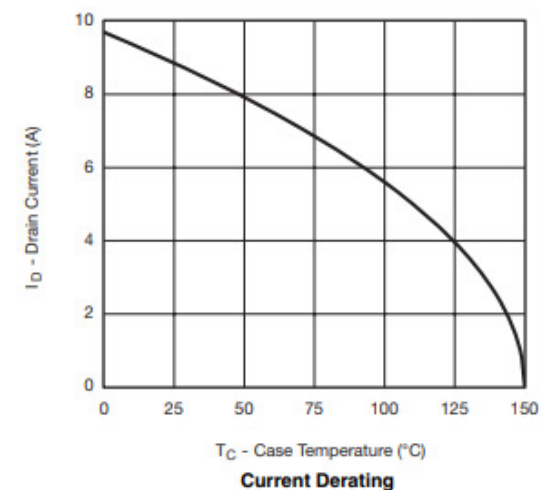
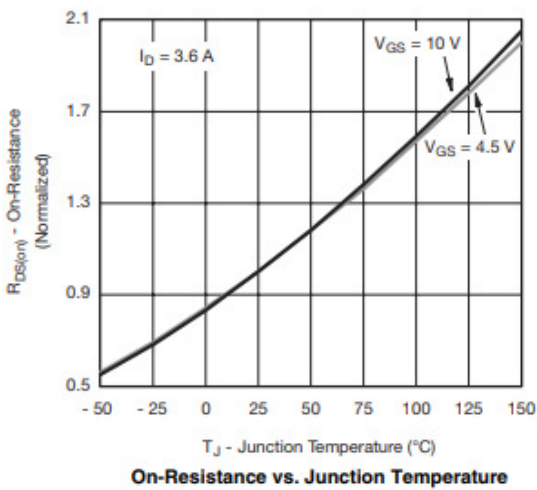
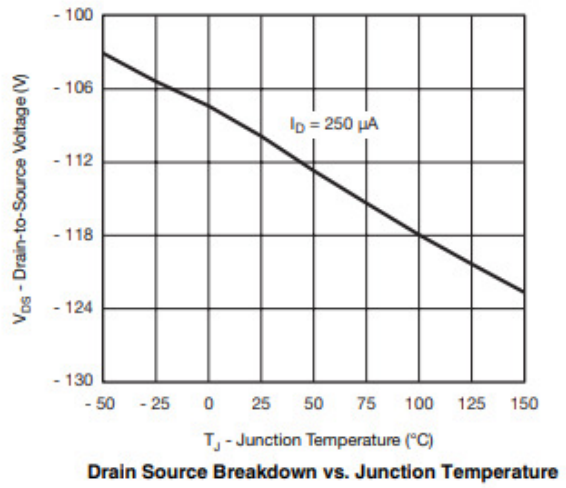
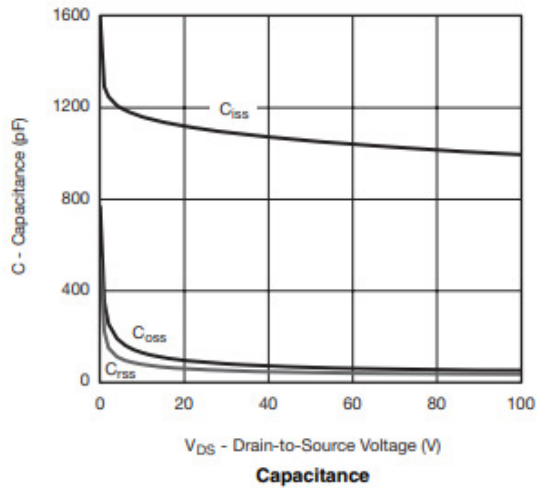
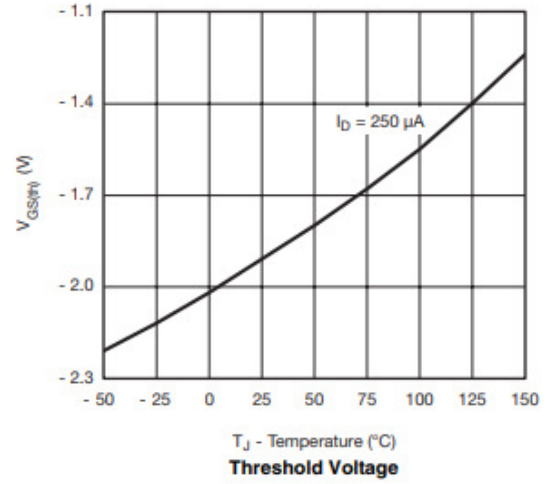
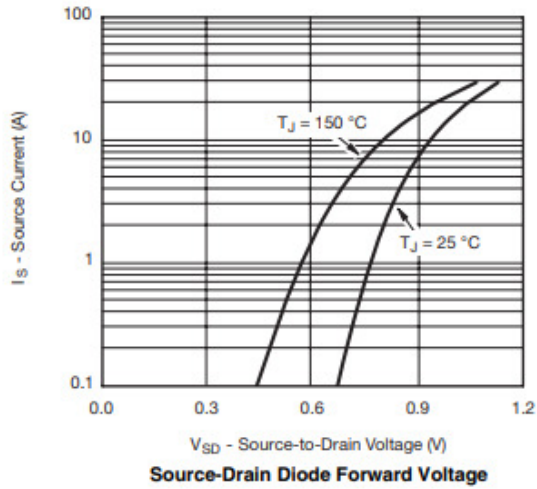
Transconductance



Gate Charge

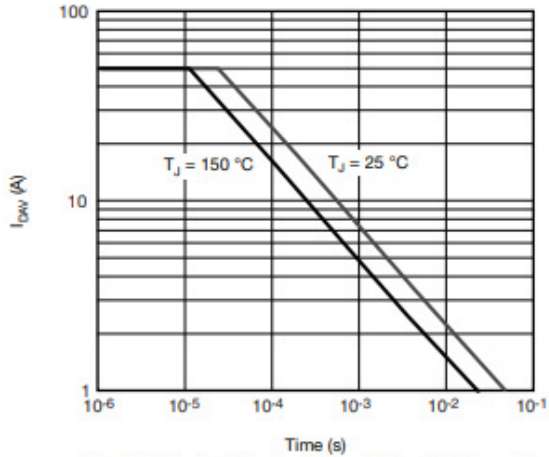


## Typical Characteristics

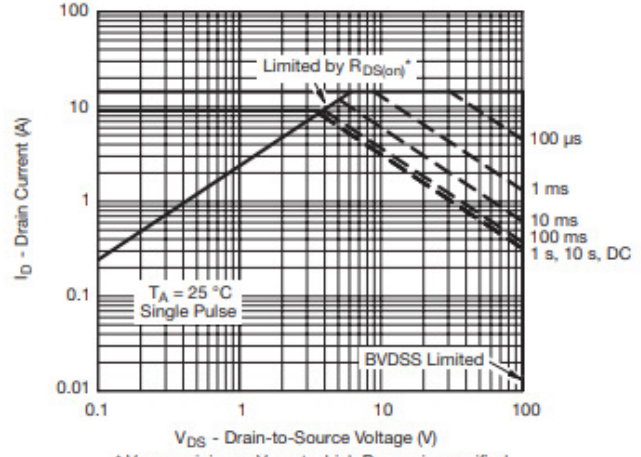




## Typical Characteristics

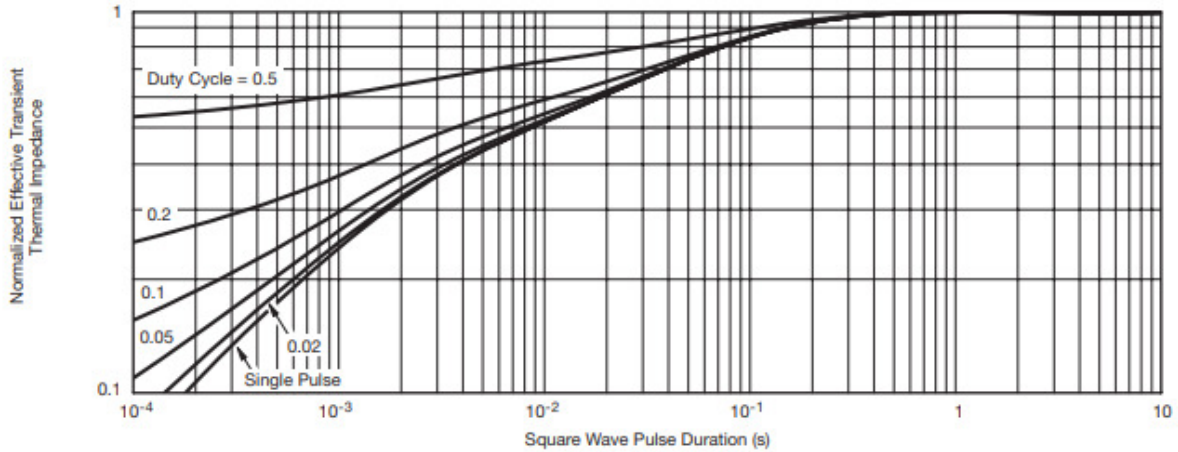


Single Pulse Avalanche Current Capability vs. Time



\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area

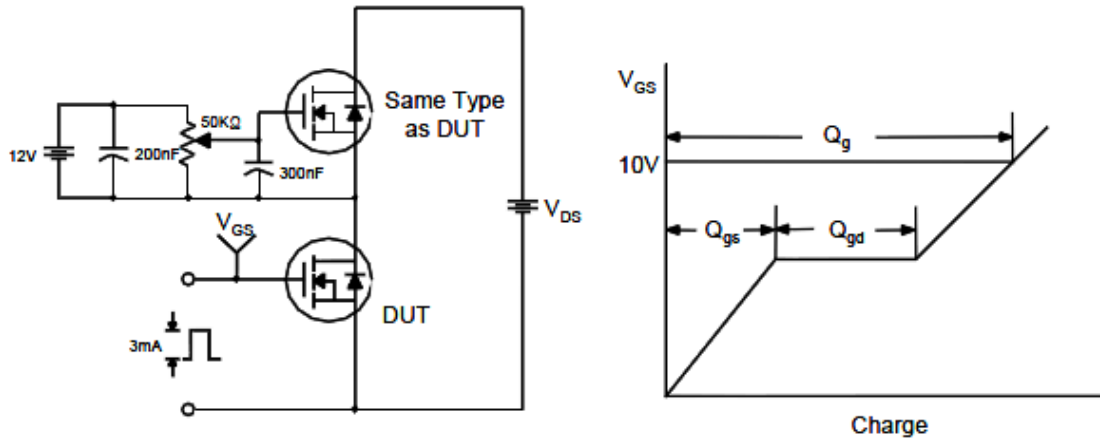


Normalized Thermal Transient Impedance, Junction-to-Case

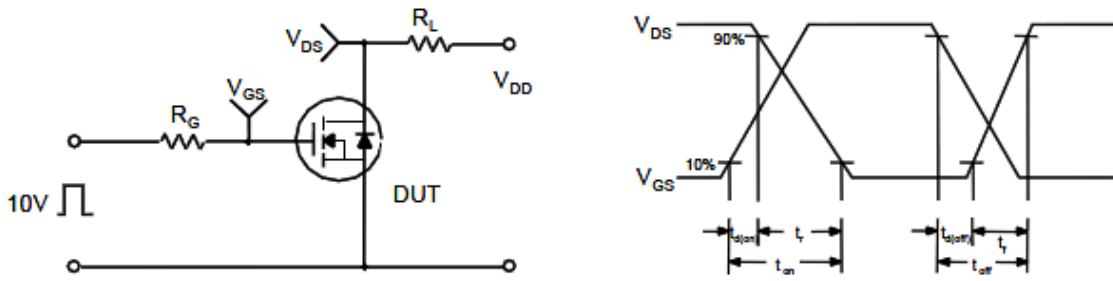


**Typical Characteristics**

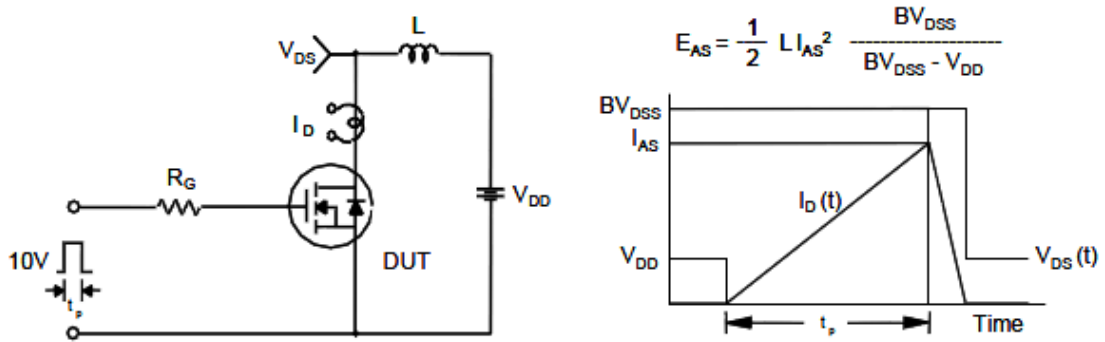
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

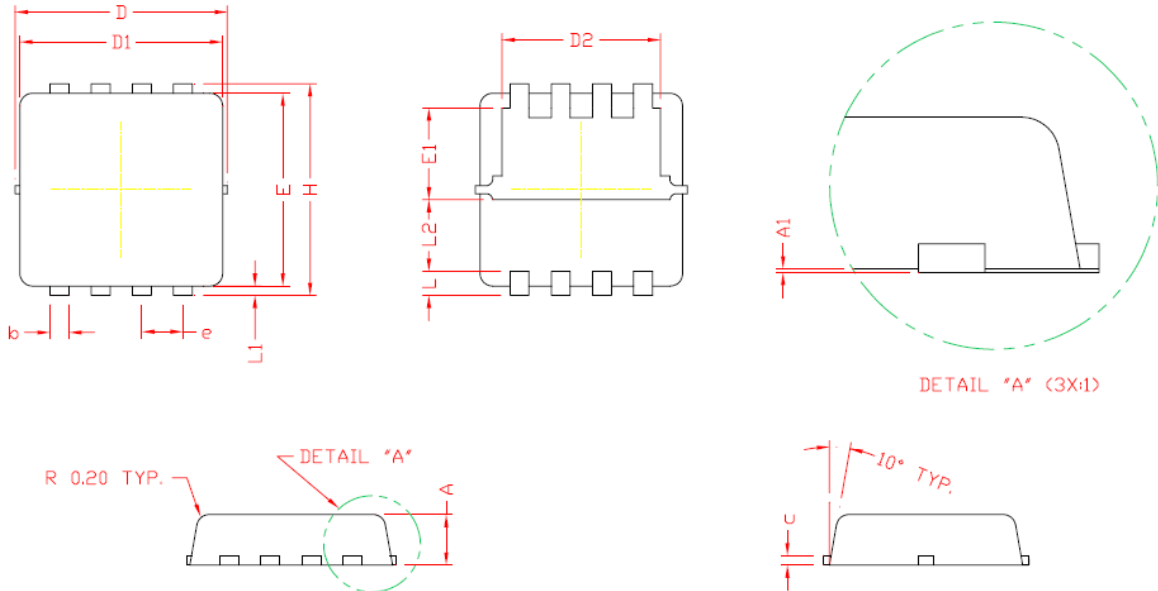


Unclamped Inductive Switching Test Circuit & Waveforms





**Package Information ( DFN3.3X3.3-8L )**



**DIMENSIONS**

REF.	Millimeters		REF.	Millimeters	
	Min.	Max.		Min.	Max.
A	0.70	0.90	E	3.00	3.20
A1	0.00	0.05	E1	1.35	1.55
b	0.24	0.35	e	0.65 BSC.	
c	0.10	0.20	H	3.20	3.40
D	3.25	3.40	L	0.30	0.50
D1	3.05	3.25	L1	0.10	0.20
D2	2.40	2.60	L2	1.13 Ref.	

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